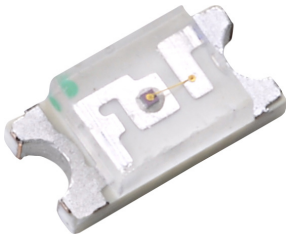


Surface Mount Green Chip LED - 1206

multicomp PRO

**RoHS
Compliant**



Features

- 3.2mm × 1.6mm SMT LED, 0.7mm Thickness.
- Wide Viewing Angle.
- Ideal for Backlight and Indicator.
- Various Colours and Lens Types Available.

Applications

- Automotive: Backlighting in dashboard and switch.
- Telecommunication: Indicator and Backlighting in telephone and fax.
- Flat Backlight for LCD switch and symbol.

Device Selection Guide

Part No.	Chip		Lens Colour
	Material	Emitted Colour	
MP005931	(InGaN)	Green	Water Clear

Absolute Maximum Ratings at T_A=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	100	mW
Forward Current	I _F	25	mA
Peak Forward Current*1	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-40°C To +85°C	
Storage Temperature	T _{stg}	-40°C To +85°C	

Notes:

*1: Pulse width ≤ 0.1ms, Duty cycle ≤ 1/10

Electrical / Optical Characteristics at T_A=25°C

Parameter	Symbol	Min.	Typ.	Max	Unit	Test Conditions
Forward Voltage	V _F	2.8	—	3.6	V	I _F =20mA
Reverse Current	I _R	—	—	10	μA	V _R =5V
Dominant Wavelength	λ _D	518	—	530	nm	I _F =20mA
Luminous Intensity	I _v	650	—	1400	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}	—	120	—	Deg.	I _F =20mA

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or chromaticity), the typical accuracy of the sorting process is as follows:

1. wavelength: ±1nm
2. Luminous Intensity: ±15%
3. Forward Voltage: ±0.1V

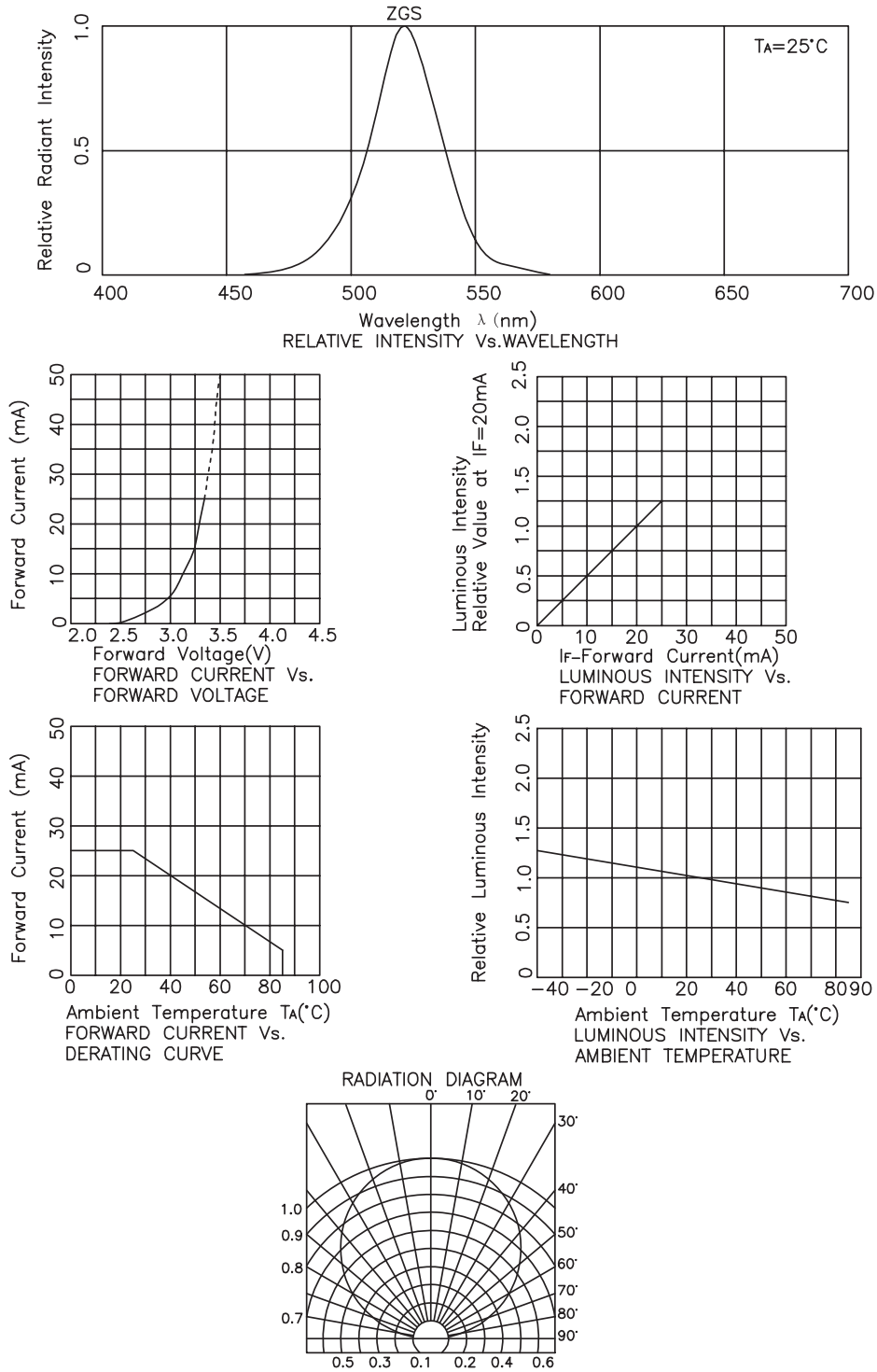
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Farnell.com/multicomp-pro
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Typical Electrical/Optical Characteristics Curves



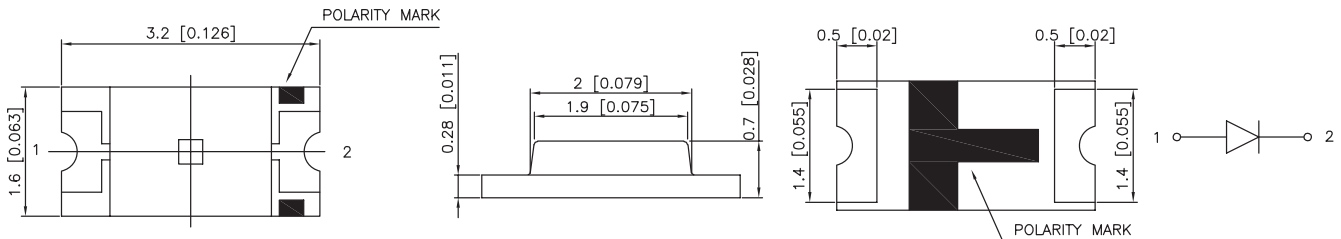
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Diagram

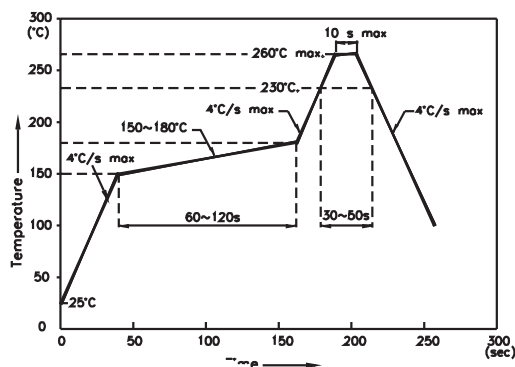


Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.15 unless otherwise noted.
3. Specifications are subject to change without notice.

Soldering Profile

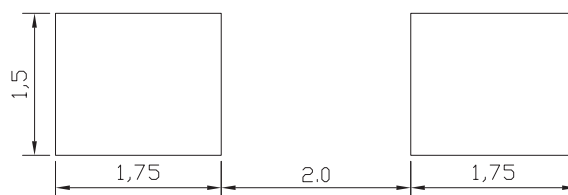
Reflow Soldering Profile For Lead-free SMT Process.



Notes

1. We recommend the reflow temperature 245°C. ($\pm 5^\circ\text{C}$) The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern



Part Number Table

Description	Part Number
SMD Chip LED, 1206, Pure Green, 1400mcd, 120°	MP005931

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